

DS91M125 125 MHz 1:4 M-LVDS Repeater with LVDS Input

Check for Samples: [DS91M125](#)

FEATURES

- DC - 125 MHz / 250 Mbps Low Jitter, Low Skew, Low Power Operation
- Independent Driver Enable Pins
- Outputs Conform to TIA/EIA-899 M-LVDS Standard
- Controlled Transition Times Minimize Reflections
- Inputs Conform to TIA/EIA-644-A LVDS Standard
- 8 kV ESD on M-LVDS Output Pins Protects Adjoining Components
- Flow-Through Pinout Simplifies PCB Layout
- Industrial Operating Temperature Range (–40°C to +85°C)
- Available in a Space Saving SOIC-16 Package

APPLICATIONS

- Multidrop / Multipoint Clock and Data Distribution
- High-Speed, Low Power, Short-Reach Alternative to TIA/EIA-485/422
- Clock Distribution in AdvancedTCA (ATCA) and MicroTCA (μTCA, uTCA) Backplanes

DESCRIPTION

The DS91M125 is a 1:4 M-LVDS repeater designed for driving and distributing clock or data signals to up to four multipoint networks.

M-LVDS (Multipoint LVDS) is a new family of bus interface devices based on LVDS technology specifically designed for multipoint and multidrop cable and backplane applications. It differs from standard LVDS in providing increased drive current to handle double terminations that are required in multipoint applications. Controlled transition times minimize reflections that are common in multipoint configurations due to unterminated stubs.

A single DS91M125 channel is a 1:4 repeater that accepts M-LVDS/LVDS/CML/LVPECL signals and converts them to M-LVDS signal levels. Each output has an associated independent driver enable pin. The DS91M125 input conforms to the LVDS standard.

The DS91M125 has a flow-through pinout for easy PCB layout. It provides a new alternative for high speed multipoint interface applications. It is packaged in a space saving SOIC-16 package.



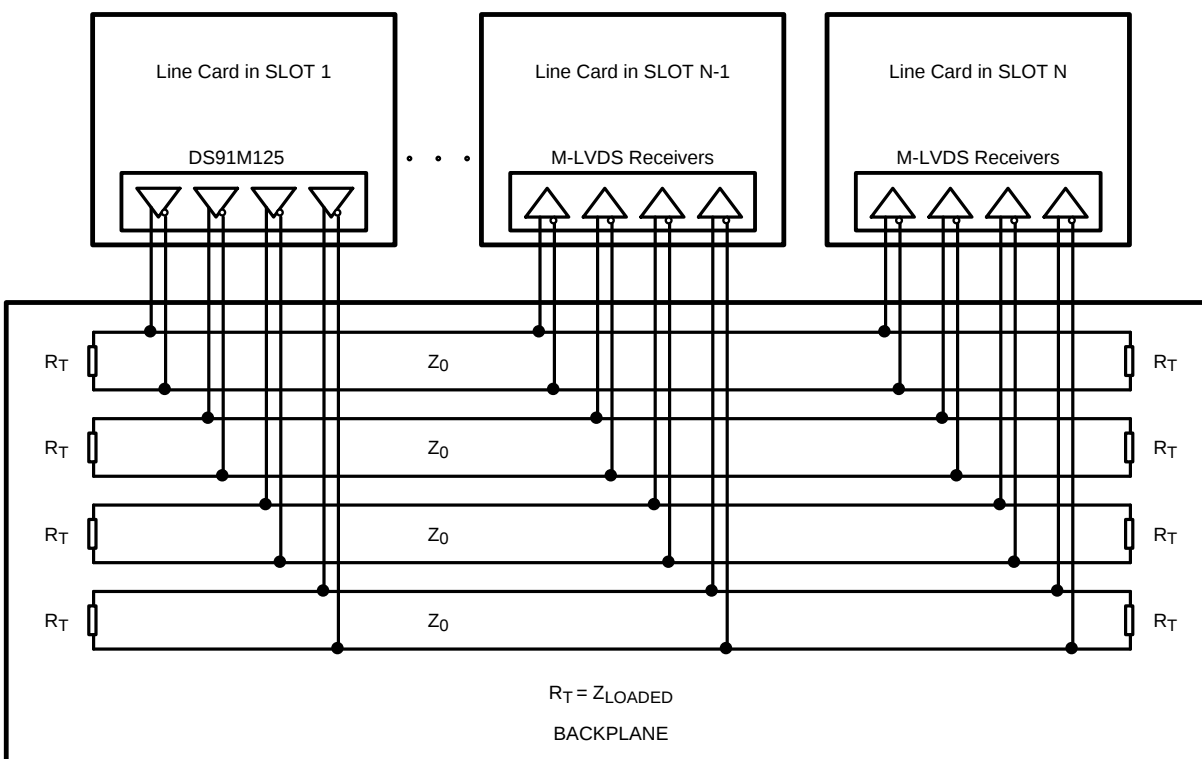
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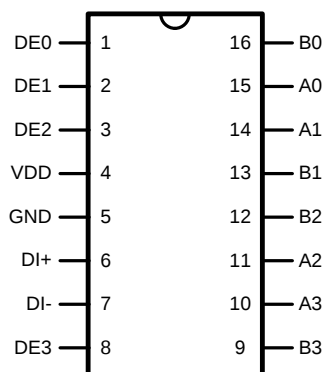
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of the Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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Typical Application

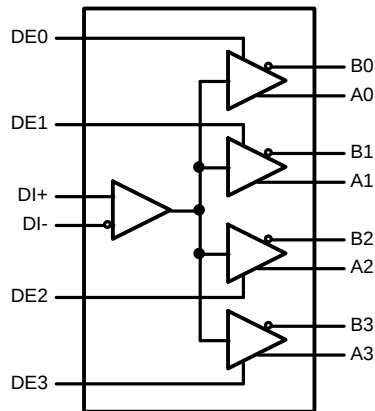


Connection Diagram



**Figure 1. 16-Lead (0.150" Wide) Molded Small Outline Package, JEDEC
See Package Number D**

Logic Diagram



PIN DESCRIPTIONS

Number	Name	I/O, Type	Description
1, 2, 3, 8	DE	I, LVCMOS	Driver enable pins: When DE is low, the driver is disabled. When DE is high, the driver is enabled. There is a 300 kΩ pulldown resistor on each pin.
6	DI+	I, LVDS	Non-inverting receiver input pin.
7	DI-	I, LVDS	Inverting receiver input pin.
5	GND	Power	Ground pin.
10, 11, 14, 15	A	O, M-LVDS	Non-inverting driver output pin.
9, 12, 13, 16	B	O, M-LVDS	Inverting driver output pin.
4	V _{DD}	Power	Power supply pin, +3.3V ± 0.3V



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

ABSOLUTE MAXIMUM RATINGS⁽¹⁾⁽²⁾

Supply Voltage		–0.3V to +4V
LVCMOS Input Voltages		–0.3V to ($V_{DD} + 0.3V$)
M-LVDS Output Voltages		–1.9V to +5.5V
LVDS Input Voltages		–0.3V to ($V_{DD} + 0.3V$)
Maximum Package Power Dissipation at +25°C	SOIC Package	2.21W
	Derate SOIC Package	19.2 mW/°C above +25°C
Thermal Resistance (4-Layer, 2 oz. Cu, JEDEC)	θ_{JA}	52°C/W
	θ_{JC}	19°C/W
Maximum Junction Temperature		140°C
Storage Temperature Range		–65°C to +150°C
Lead Temperature (Soldering, 4 seconds)		260°C
ESD Susceptibility	HBM ⁽³⁾	≥ 8 kV
	MM ⁽⁴⁾	≥ 250V
	CDM ⁽⁵⁾	≥ 1250V

(1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur, including inoperability and degradation of device reliability and/or performance. Functional operation of the device and/or non-degradation at the Absolute Maximum Ratings or other conditions beyond those indicated in the Recommended Operating Conditions is not implied. The Recommended Operating Conditions indicate conditions at which the device is functional and the device should not be operated beyond such conditions.

(2) If Military/Aerospace specified devices are required, please contact the TI Sales Office/ Distributors for availability and specifications.

(3) Human Body Model, applicable std. JESD22-A114C

(4) Machine Model, applicable std. JESD22-A115-A

(5) Field Induced Charge Device Model, applicable std. JESD22-C101-C

RECOMMENDED OPERATING CONDITIONS

	Min	Typ	Max	Units
Supply Voltage, V_{DD}	3.0	3.3	3.6	V
Voltage at M-LVDS Outputs	–1.4		+3.8	V
Voltage at LVDS Inputs	0		V_{DD}	V
LVCMOS Input Voltage High V_{IH}	2.0		V_{DD}	V
LVCMOS Input Voltage Low V_{IL}	0		0.8	V
Operating Free Air Temperature T_A	–40	+25	+85	°C

ELECTRICAL CHARACTERISTICS

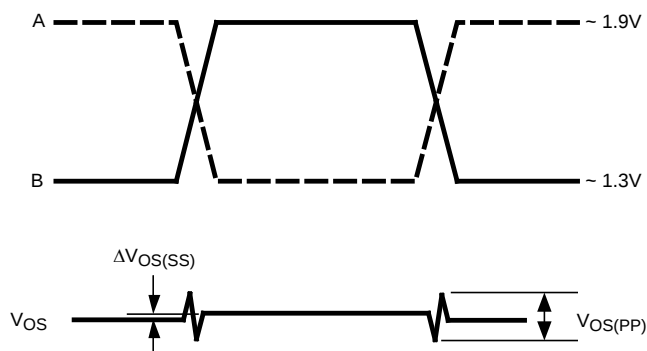
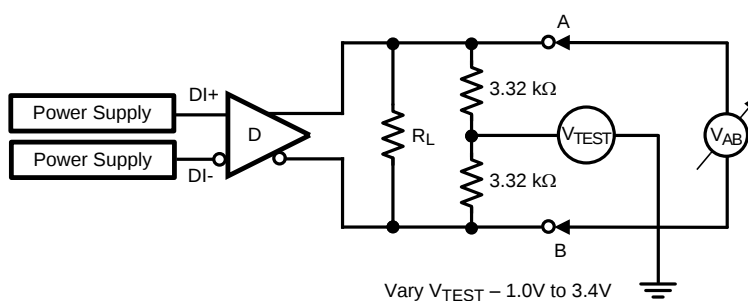
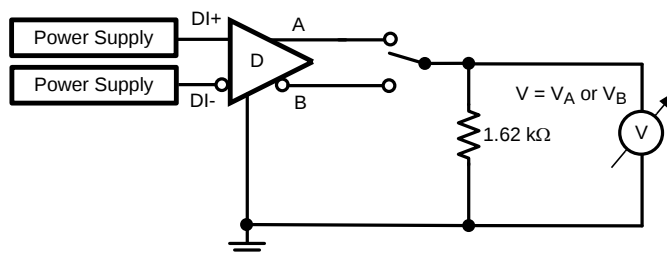
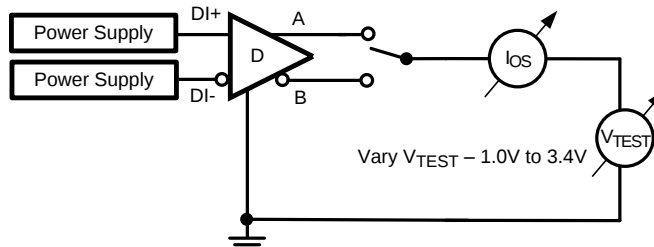
Over recommended operating supply and temperature ranges unless otherwise specified. ⁽¹⁾⁽²⁾⁽³⁾⁽⁴⁾

Symbol	Parameter	Conditions	Min	Typ	Max	Units
LVC MOS DC Specifications						
V_{IH}	High-Level Input Voltage		2.0		V_{DD}	V
V_{IL}	Low-Level Input Voltage		GND		0.8	V
I_{IH}	High-Level Input Current	$V_{IH} = 3.6V$	-15	± 1	15	μA
I_{IL}	Low-Level Input Current	$V_{IL} = 0V$	-15	± 1	15	μA
V_{CL}	Input Clamp Voltage	$I_{IN} = -18\text{ mA}$	-1.5			V
M-LVDS Driver DC Specifications						
$ V_{AB} $	Differential output voltage magnitude	$R_L = 50\Omega$, $C_L = 5pF$	480		650	mV
ΔV_{AB}	Change in differential output voltage magnitude between logic states	See Figure 2 and Figure 4	-50	0	+50	mV
$V_{OS(SS)}$	Steady-state common-mode output voltage	$R_L = 50\Omega$, $C_L = 5pF$	0.3	1.6	2.1	V
$ \Delta V_{OS(SS)} $	Change in steady-state common-mode output voltage between logic states	See Figure 2 and Figure 3	0		+50	mV
$V_{A(OC)}$	Maximum steady-state open-circuit output voltage	See Figure 5	0		2.4	V
$V_{B(OC)}$	Maximum steady-state open-circuit output voltage		0		2.4	V
$V_{P(H)}$	Voltage overshoot, low-to-high level output	$R_L = 50\Omega$, $C_L = 5pF$, $C_D = 0.5pF$ See Figure 7 and Figure 8 ⁽⁵⁾			$1.2V_{SS}$	V
$V_{P(L)}$	Voltage overshoot, high-to-low level output		-0.2V SS			V
I_{OS}	Differential short-circuit output current	See Figure 6 ⁽⁶⁾	-43		43	mA
I_A	Driver output current	$V_A = 3.8V$, $V_B = 1.2V$			32	μA
		$V_A = 0V$ or $2.4V$, $V_B = 1.2V$	-20		+20	μA
		$V_A = -1.4V$, $V_B = 1.2V$	-32			μA
I_B	Driver output current	$V_B = 3.8V$, $V_A = 1.2V$			32	μA
		$V_B = 0V$ or $2.4V$, $V_A = 1.2V$	-20		+20	μA
		$V_B = -1.4V$, $V_A = 1.2V$	-32			μA
I_{AB}	Driver output differential current ($I_A - I_B$)	$V_A = V_B$, $-1.4V \leq V \leq 3.8V$	-4		+4	μA
$I_{A(OFF)}$	Driver output power-off current	$V_A = 3.8V$, $V_B = 1.2V$, $DE = 0V$ $0V \leq V_{DD} \leq 1.5V$			32	μA
		$V_A = 0V$ or $2.4V$, $V_B = 1.2V$, $DE = 0V$ $0V \leq V_{DD} \leq 1.5V$	-20		+20	μA
		$V_A = -1.4V$, $V_B = 1.2V$, $DE = 0V$ $0V \leq V_{DD} \leq 1.5V$	-32			μA

- (1) The Electrical Characteristics tables list ensured specifications under the listed Recommended Operating Conditions except as otherwise modified or specified by the Electrical Characteristics Conditions and/or Notes. Typical specifications are estimations only and are not ensured.
- (2) Current into device pins is defined as positive. Current out of device pins is defined as negative. All voltages are referenced to ground except V_{OD} and ΔV_{OD} .
- (3) Typical values represent most likely parametric norms for $V_{DD} = +3.3V$ and $T_A = +25^\circ C$, and at the Recommended Operation Conditions at the time of product characterization and are not ensured.
- (4) C_L includes fixture capacitance and C_D includes probe capacitance.
- (5) Specification is ensured by characterization and is not tested in production.
- (6) Output short circuit current (I_{OS}) is specified as magnitude only, minus sign indicates direction only.

ELECTRICAL CHARACTERISTICS (continued)Over recommended operating supply and temperature ranges unless otherwise specified.⁽¹⁾⁽²⁾⁽³⁾⁽⁴⁾

Symbol	Parameter	Conditions	Min	Typ	Max	Units
$I_{B(OFF)}$	Driver output power-off current	$V_B = 3.8V, V_A = 1.2V,$ $DE = 0V$ $0V \leq V_{DD} \leq 1.5V$			32	μA
		$V_B = 0V \text{ or } 2.4V, V_A = 1.2V,$ $DE = 0V$ $0V \leq V_{DD} \leq 1.5V$	-20		+20	μA
		$V_B = -1.4V, V_A = 1.2V,$ $DE = 0V$ $0V \leq V_{DD} \leq 1.5V$	-32			μA
$I_{AB(OFF)}$	Driver output power-off differential current ($I_{A(OFF)} - I_{B(OFF)}$)	$V_A = V_B, -1.4V \leq V \leq 3.8V,$ $DE = 0V$ $0V \leq V_{DD} \leq 1.5V$	-4		+4	μA
C_A	Driver output capacitance	$V_{DD} = \text{OPEN}$		7.8		pF
C_B	Driver output capacitance			7.8		pF
C_{AB}	Driver output differential capacitance			3		pF
$C_{A/B}$	Driver output capacitance balance (C_A/C_B)			1		
LVDS Receiver DC Specifications						
V_{IT+}	Positive-going differential input voltage threshold			-5	100	mV
V_{IT-}	Negative-going differential input voltage threshold		-100	-5		mV
V_{CMR}	Common mode voltage range	$V_{ID} = 100 \text{ mV}$	0.05		$V_{DD} - 0.05$	V
I_{IN}	Input current	$V_{IN} = 3.6V, V_{DD} = 3.6V$		± 1	± 10	μA
		$V_{IN} = 0V, V_{DD} = 3.6V$		± 1	± 10	μA
C_{IN}	Input capacitance	$V_{DD} = \text{OPEN}$		5		pF
POWER SUPPLY CURRENT						
I_{CCD}	Driver Supply Current	$R_L = 50\Omega, DE = V_{DD}$		67	78	mA
I_{CCZ}	TRI-STATE Supply Current	$DE = \text{GND}$		21	26	mA

**Figure 3. Differential Driver Waveforms****Figure 4. Differential Driver Full Load Test Circuit****Figure 5. Differential Driver DC Open Test Circuit****Figure 6. Differential Driver Short-Circuit Test Circuit**

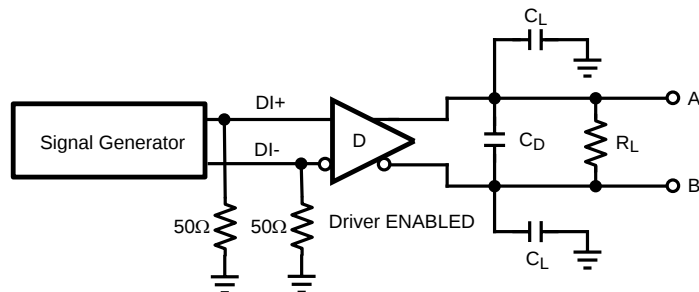


Figure 7. Driver Propagation Delay and Transition Time Test Circuit

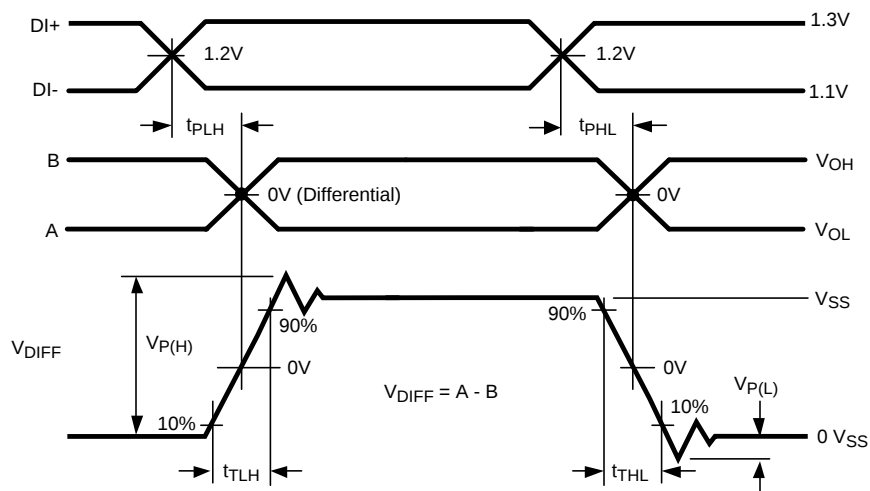


Figure 8. Driver Propagation Delays and Transition Time Waveforms

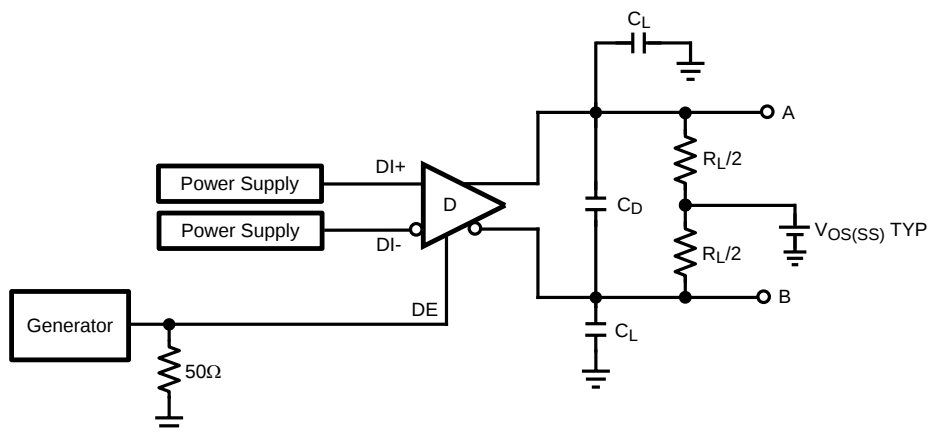


Figure 9. Driver TRI-STATE Delay Test Circuit

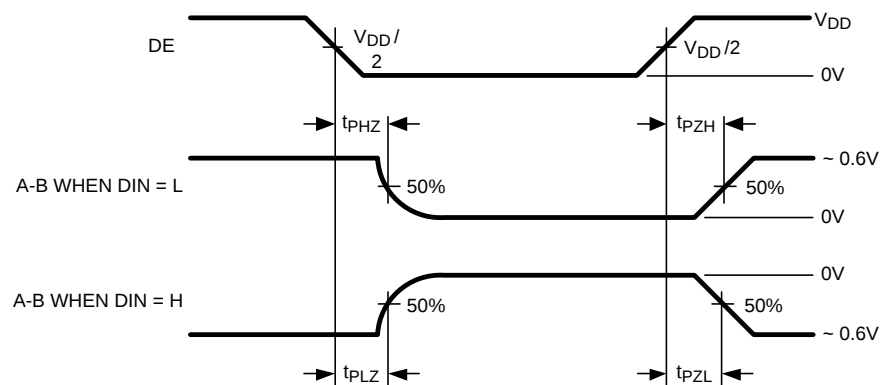


Figure 10. Driver TRI-STATE Delay Waveforms

TYPICAL PERFORMANCE CHARACTERISTICS

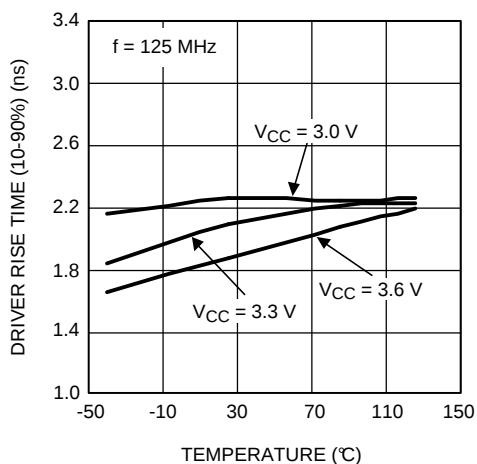


Figure 11. Driver Rise Time as a Function of Temperature

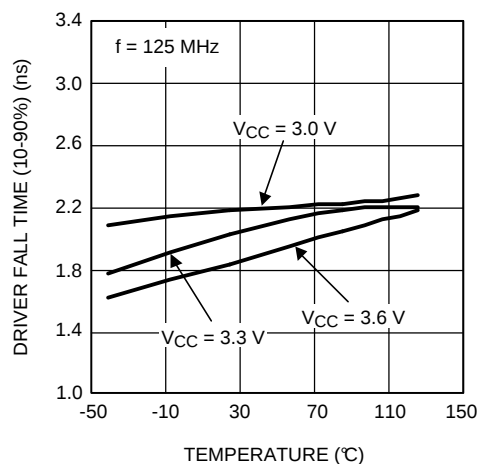


Figure 12. Driver Fall Time as a Function of Temperature

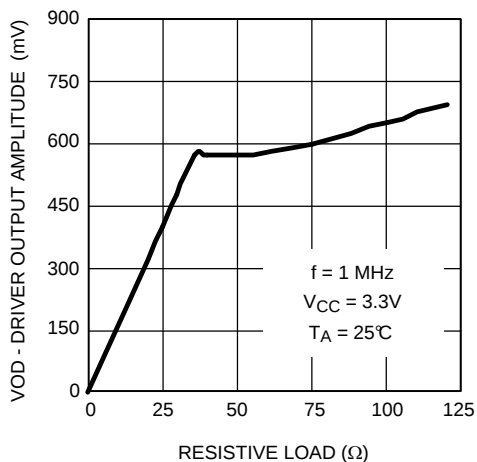


Figure 13. Driver Output Signal Amplitude as a Function of Resistive Load

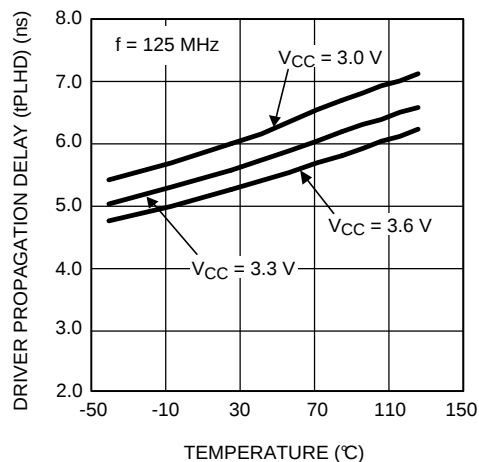


Figure 14. Driver Propagation Delay (tPLHD) as a Function of Temperature

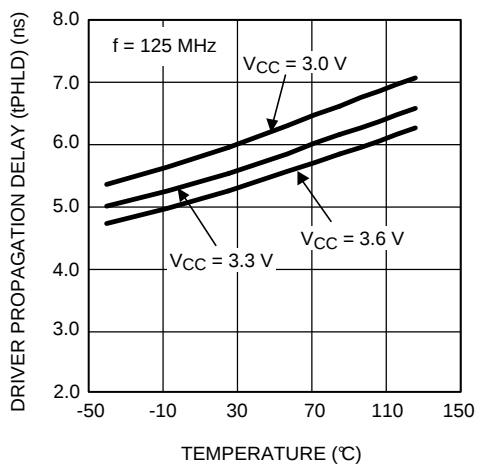


Figure 15. Driver Propagation Delay (tPHLD) as a Function of Temperature

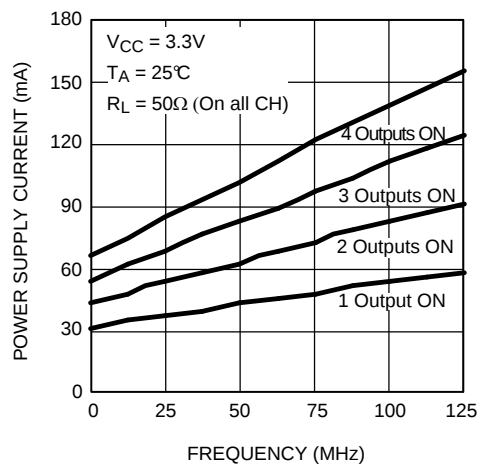


Figure 16. Driver Power Supply Current as a Function of Frequency

REVISION HISTORY

Changes from Revision B (April 2013) to Revision C	Page
• Changed layout of National Data Sheet to TI format	11

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
DS91M125TMA/NOPB	Active	Production	SOIC (D) 16	48 TUBE	Yes	SN	Level-1-260C-UNLIM	-40 to 85	DS91M125 TMA
DS91M125TMA/NOPB.A	Active	Production	SOIC (D) 16	48 TUBE	Yes	SN	Level-1-260C-UNLIM	-40 to 85	DS91M125 TMA
DS91M125TMAX/NOPB	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	DS91M125 TMA
DS91M125TMAX/NOPB.A	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	DS91M125 TMA

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
DS91M125TMAX/NOPB	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.3	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
DS91M125TMAX/NOPB	SOIC	D	16	2500	367.0	367.0	35.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
DS91M125TMA/NOPB	D	SOIC	16	48	495	8	4064	3.05
DS91M125TMA/NOPB.A	D	SOIC	16	48	495	8	4064	3.05

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4040047-6/M 06/11

NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.

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